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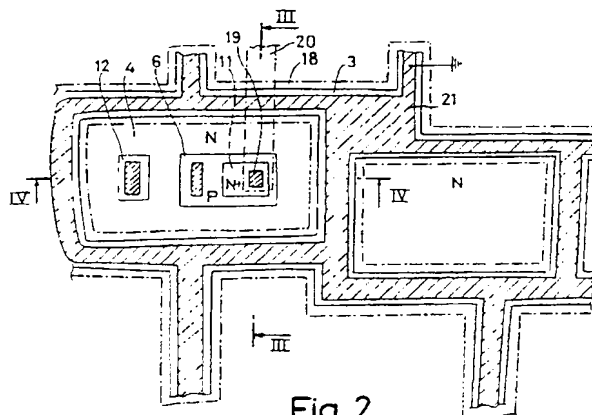
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I-20131 Milano(IT)**(54) **Monolithic vertical-type semiconductor power device with a protection against parasitic currents.**

(57) The monolithic vertical-type semiconductor power device comprises an N⁺ type substrate (1) over which there is superimposed an N- type epitaxial layer (2) in which there is obtained aP type insulation pocket (3). Such pocket contains N type regions (4, 15) and P type regions (8) which in turn contain N⁺ type regions (11, 12; 13; 14) and of P type regions (6, 7, 9, 10) which define circuit components

(T1, T2, T5) of the device. Insulation pocket (3) is wholly covered by a first metallisation (21, 30) connected to ground. Such metallisation (21, 30) is in turn protected by a layer of insulating material (18) suitable for allowing the crossing of metal tracks (20) or of a second metallisation (31) for the connection of the different components.

**Fig.2****EP 0 429 131 A2**

MONOLITHIC VERTICAL-TYPE SEMICONDUCTOR POWER DEVICE WITH A PROTECTION AGAINST PARASITIC CURRENTS

The present invention relates to a monolithic vertical-type semiconductor power device with a protection against parasitic currents.

A vertical-type semiconductor integrated structure comprises essentially an N+ type substrate over which there is superimposed an N- type epitaxial layer in which there is obtained, a P type insulation pocket with protruding extremities, connected to ground. The insulation pocket contains N type regions which include P and N+ type regions which define circuit components of the device. On the bottom of the N regions there are also N+ type regions.

With the circuit's active components there are associated parasite components which switch on when the circuit's active components associated with them are switched on, and inject current in the central part of insulation pocket P.

The injected current flows through the insulation pocket and reaches the grounded metallic terminal.

If such terminal is far from the injection area, the insulation pocket itself rises in voltage since the resistive path which the current must follow to reach the grounded terminal is longer.

Such a voltage rise, which can be even of some volts, can jeopardize the operation of the integrated circuit.

In addition, in the case in which the N+ type substrate goes to a low voltage while the insulation pocket rises in voltage, a parasite junction diode between such regions enters into conduction injecting current into the substrate and thus jeopardizing the operation of the whole.

From such circuit behaviours it is possible to understand the need for grounding pocket P at as many points as possible. Such problem is generally solved by connecting between them a substantial number of ground contacts on insulation pocket P by means of a metal track which is then grounded. Such a process is that much more complicated the greater is the number of ground contacts made and requires a substantial size since the metal ground tracks must be compatible with the several connection tracks of the different circuit elements.

The object of the present invention is to overcome the abovementioned drawbacks, caused by the presence of selective ground contacts of the insulation pocket.

According to the invention such object is attained with a monolithic vertical-type semiconductor power device comprising an N+ type substrate in which there is obtained a P type insulation

pocket with extremities protruding over the surface of the substrate, which in turn contains N type regions and P type regions for the containment of N+ type regions and of P type regions which define circuit components of the device, characterized in that said protruding extremities of the insulation pocket are wholly covered by a first metalisation connected to ground.

In this way the resistive path between the area of injection of the current into the insulation pocket on the part of the parasite components and the grounded terminal is in any case short and does not originate the drawbacks described above.

The features of the present invention shall be made more evident by the following detailed description of embodiments illustrated by way of non-limiting examples in the enclosed drawings, wherein:

Fig. 1 illustrates a longitudinal sectional view of a monolithic vertical-type semiconductor power device not provided with protection according to the invention;

Fig. 2 shows a top plan view of a first embodiment of the monolithic power device according to the invention, provided with protection against parasitic currents;

Fig. 3 is a sectional view of Fig. 2 taken along the line III-III;

Fig. 4 is a sectional view of Fig. 2 taken along the line IV-IV;

Fig. 5 is a top plan view of a second embodiment of the monolithic power device according to the invention;

Fig. 6 is a sectional view of Fig. 5 taken along the line VI-VI.

With reference to Fig. 1 the monolithic power device comprises an N+ type substrate 1 on which there is made to grow an N- type epitaxial layer 2, in which there is obtained a P type insulation pocket 3 with extremities protruding over the surface of the substrate. Region 1 and pocket 3 form a diode D1.

Inside pocket 3 there are obtained N type regions 4, 15 for the containment of the circuit's active components. Inside region 4 there are obtained a P type region 6 and N+ type regions 11, 12. Region 12 constitutes the collector of a transistor T1 whose emitter is accomplished in region 11 and whose base is accomplished in region 6. Inside region 15 there are obtained P type regions 7, 9, 10, and an N+ type region 13. Region 13 constitutes the base of a transistor T2 whose collector is accomplished in region 7, in turn connected to region 10, and whose emitter is accom-

plished in region 9. between region 15 and pocket 3 there is also accomplished a diode D2.

On the bottom of regions 4, 15 there are obtained N+ type regions 16, 17. Such regions 16, 17 constitute the bases of a first parasite transistor T4 whose emitter is accomplished in region 6 and whose collector is accomplished in pocket 3 and of a second parasite transistor T3 whose emitter is accomplished in the P type region 9 and whose collector is accomplished in pocket 3.

In addition, inside the epitaxial layer 2 there is obtained a P type region 8 and inside this an N+ type region 14. Region 8 constitutes the base of a power transistor T5, whose emitter is accomplished in region 14 and whose collector is accomplished in the epitaxial layer 2 until it reaches substrate 1.

With reference to the operation of the circuit illustrated in Fig. 1, when transistor T2 is on, the parasite transistor T3 corresponding to it is also on; when transistor T1 is in saturation, parasite transistor T4 corresponding to it is active.

When parasite transistors T3 and T4 are on they inject current into insulation pocket P, region 3. Such a current flows through insulation pocket 3, and reaches the grounded terminal. If this terminal is far from the area where the current is injected into the insulation pocket, the pocket rises in voltage since the resistive path which the current must follow to reach the ground terminal is longer.

The voltage rise of insulation pocket P can be even of some volts and when the N type regions 4, 15 contained in insulation pocket P go to a low voltage the conduction of parasite transistors T3, T4 can jeopardize the operation of the integrated circuit.

The voltage rise of insulation pocket P in combination with the drop in voltage in the N type region 15 causes moreover the conduction of diode D2.

Substrate 1, used as the collector of vertical power transistor T5, can also go to a very low voltage at the saturation point of the transistor. If between substrate 1 and insulation pocket 3 there is a voltage difference that is higher than the threshold conduction voltage of diode D1, the latter goes into conduction and jeopardizes the operation of the entire circuit.

To overcome the voltage rise in insulation pocket P caused by the existence of the parasite transistors, with reference to Figs 2, 3, 4, the protruding extremities of insulation pocket P are, according to the invention, wholly covered by a metallisation 21, say a layer of metal polysilicide, preferably of platinum, whose resistance is approximately 1 ohm per square, that is about 100 times lower than the resistance per square of insulation pocket P. Some areas of insulation pocket P are reached and contacted by metal tracks of al-

luminium, not shown, connected to ground according to the prior art.

In this way the leakage currents of parasite transistors T3, T4 are conveyed to ground through low-resistivity paths and thus there is no rise in voltage in insulation pocket P.

Metallisation 21 is in turn covered by an insulating layer 18, say, silicon oxide, to allow the crossing of metallisation 21 on the part of metal tracks 20 connecting the different circuit elements of the integrated circuit, reached at bump contacts 19.

With reference to fig.s 5 and 6 an alternative embodiment of the device according to the invention provides for the deposition, over the protruding extremities of insulation pocket P, of a first metallisation 30 suitable for forming the grounding network, over which there are superimposed an insulation layer 40 and a second metallisation 31 connecting the different circuit elements of the integrated circuit. Both metallisations are preferably accomplished in aluminium, while for the insulation layer silicon oxide is preferably used.

Claims

1. Monolithic vertical-type semiconductor power device comprising an N+ type substrate (1) in which there is obtained a P type insulation pocket (3) with extremities protruding over the surface of the substrate, which in turn contains N type regions (4, 15) and P type regions (8) for the containment of N+ type regions (11, 12; 13; 14) and of P type regions (6, 7, 9, 10) which define circuit components of the device, characterized in that said protruding extremities of the insulation pocket (3) are wholly covered by a first metallisation (21, 30) connected to ground.
2. Device according to claim 1, characterized in that said first metallisation (21) is accomplished in metal silicide.
3. Device according to claim 2, characterized in that said first metallisation (21) is accomplished in platinum silicide.
4. Device according to claim 1, characterized in that said first metallisation (30) is accomplished in aluminium.
5. Device according to claim 1, characterized in that said first metallisation (21, 30) is covered by a layer of insulating material (18, 40).
6. Device according to claim 5, characterized in that said layer of insulating material (18) is accomplished in silicon oxide.
7. Device according to claim 5, characterized in that on the layer of insulating material (18) there are metal tracks (20) connecting the different circuit elements.

8. Device according to claim 7, characterized in that said metal connecting tracks (20) are accomplished in aluminium.

9. Device according to claim 5, characterized in that on the layer of insulating material (40) there is a second metallisation (31) connecting the different circuit elements.

10. Device according to claim 9, characterized in that said second metallisation (ii) is accomplished in aluminium.

11. Device according to claim 1, characterized in that said insulation pocket (3) is obtained in an epitaxial layer (2) superimposed over said substrate (1).

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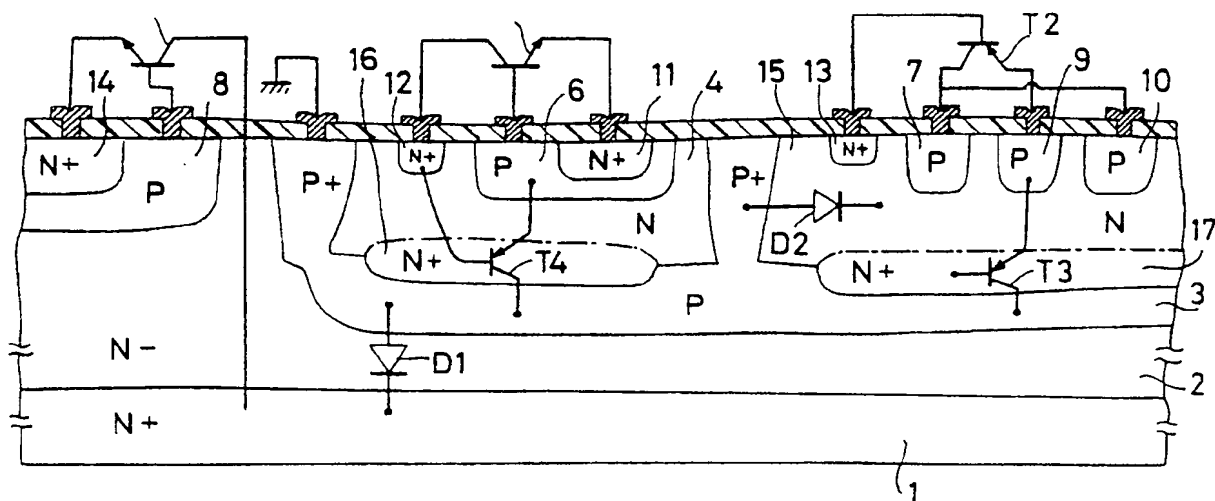


Fig.1

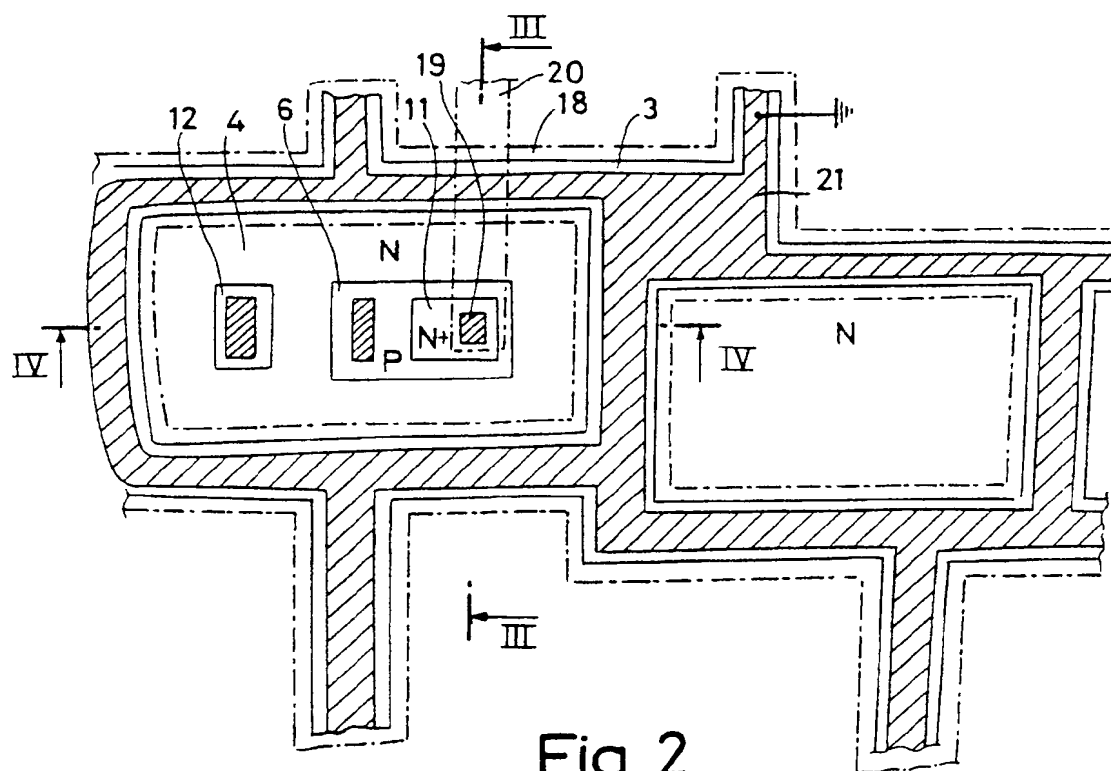


Fig. 2

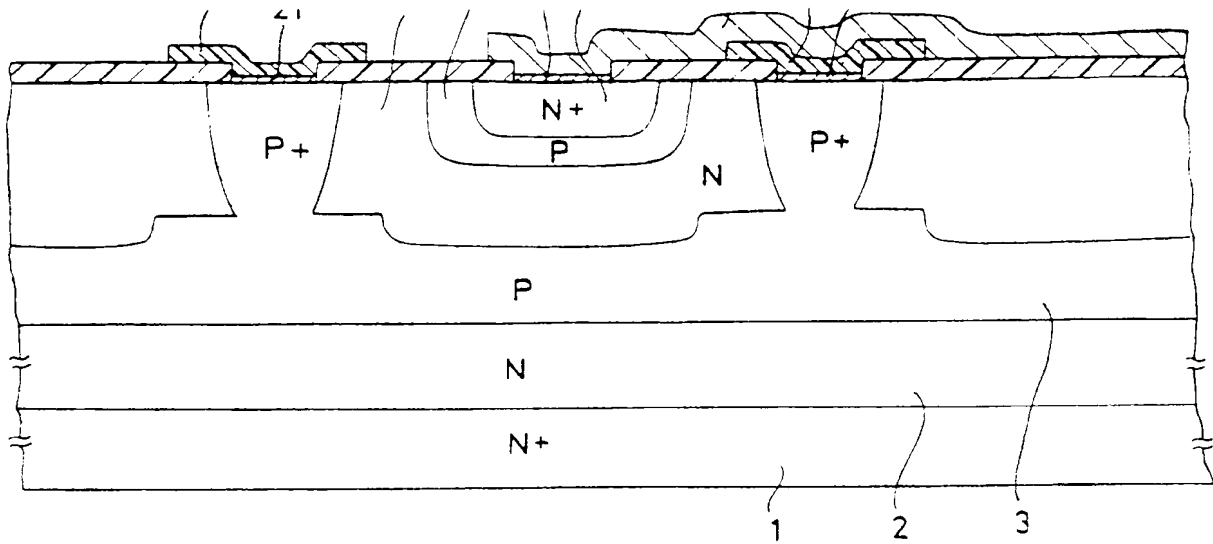


Fig. 3

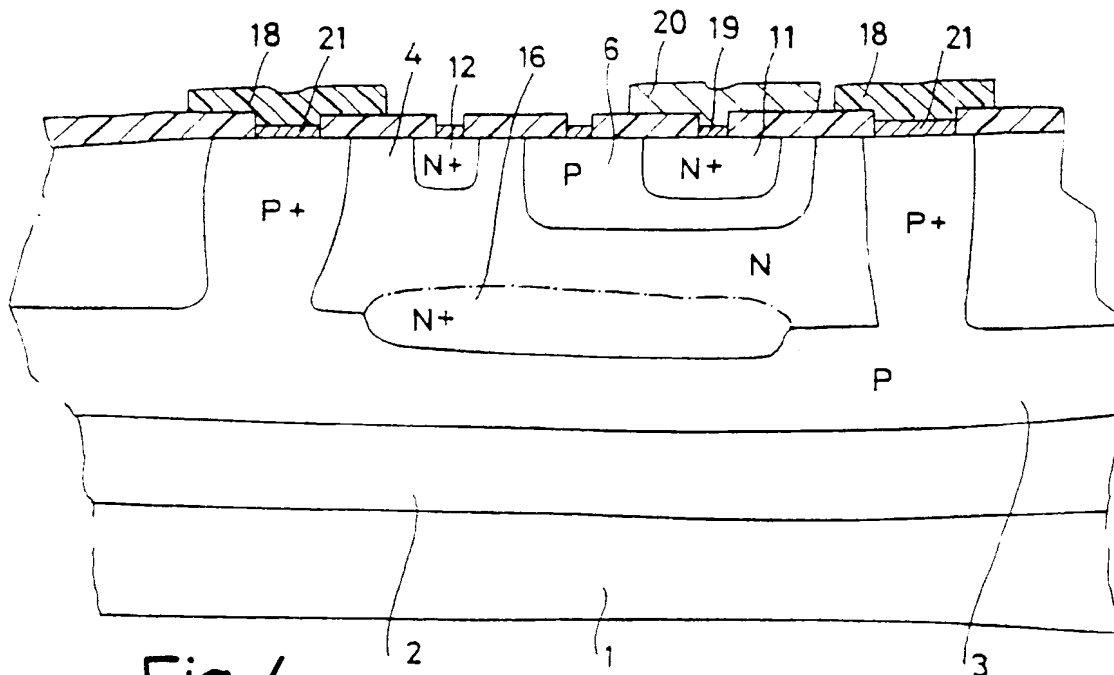


Fig. 4

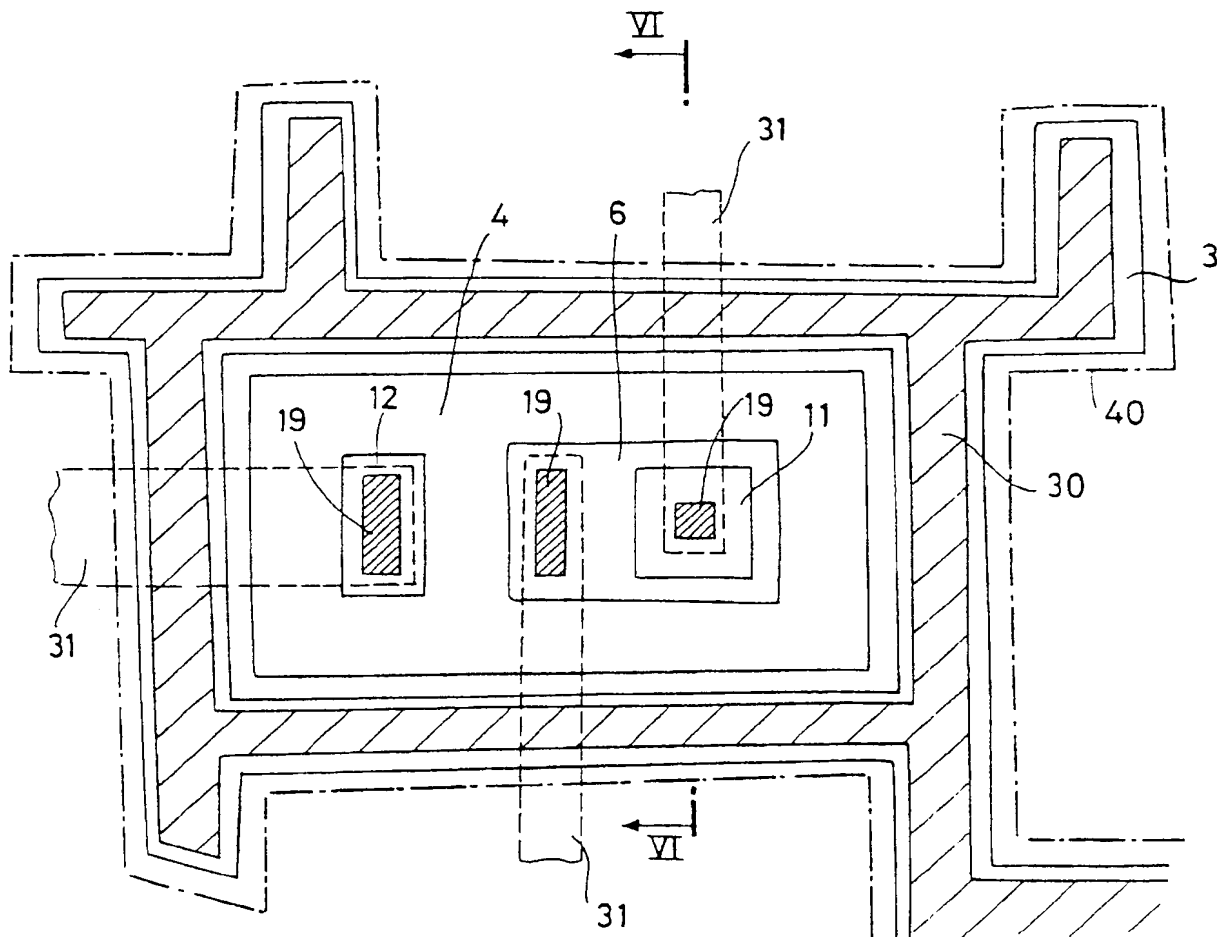


Fig. 5

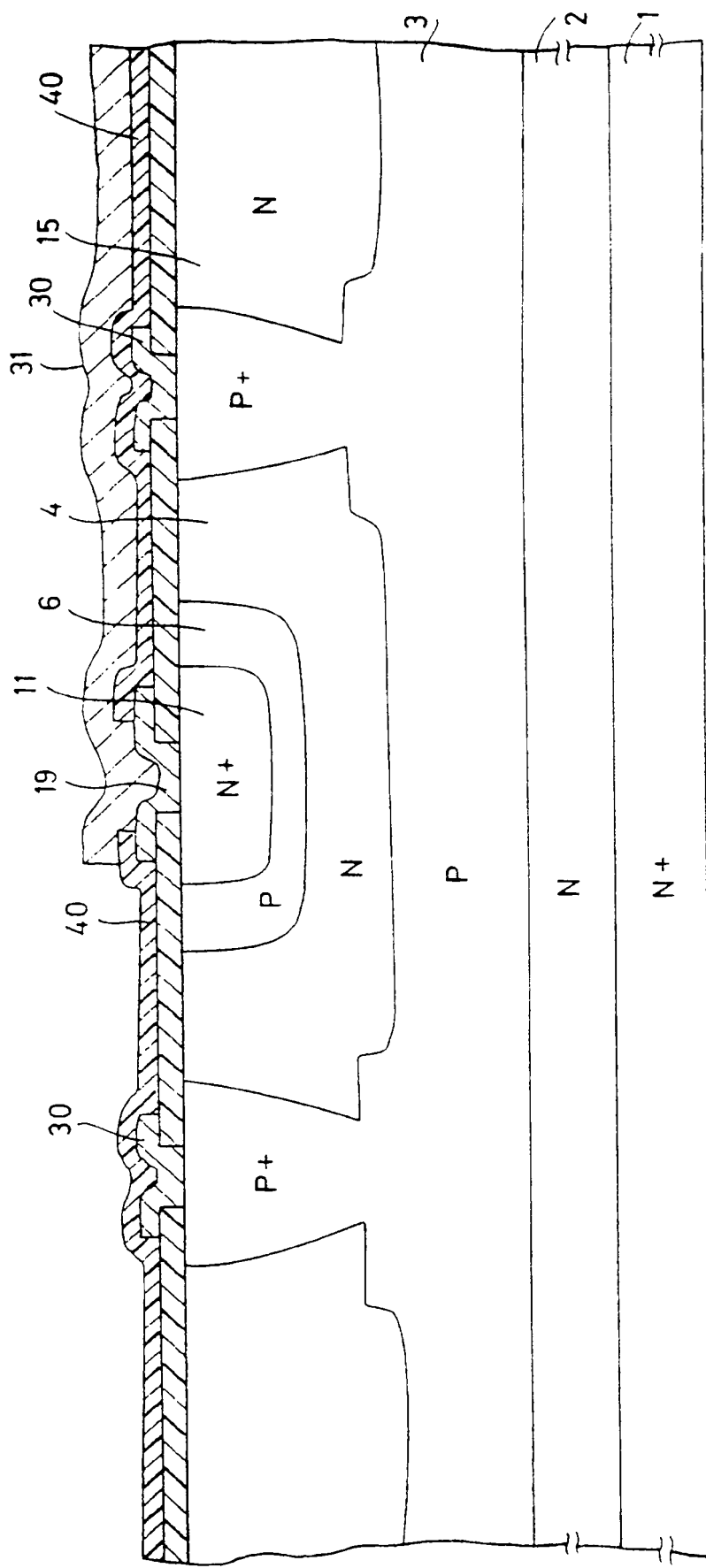


Fig. 6